



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.020mm	3.5	
1	Top Layer	Copper	0.040mm		
	Dielectric 1	Core-043	1.499mm	4.3	
2	Bottom Layer	Copper	0.040mm		
	Bottom Solder	Solder Resist	0.020mm	3.5	
	Bottom Overlay				

PCB NOTES

1. Number of layers - 2
2. Board size - 80mm x 58mm. Tolerance - +/- 0.1mm
3. Board thickness - 1.6mm +/-10%
4. Material - FR-4 High Tg, cooper thickness is 35um (1oz)
5. Solder Mask - Two sides, Green, Liquid. Solder mask mis-registration +/-0.025mm. No overlap permitted on SMD lands. Solder Mask is in accordance with IPC-SM-840 D, Class H
6. Silkscreen - TOP side only
7. Type of coating - ENIG
8. Electrical Test on both sides
9. Min dia of plated hole - 0.3mm
10. Min annular ring - 0.15mm
11. Min trace width - 0.2mm
12. Min clearance - 0.2mm
13. Impedance control - No